# **LNJ306G5TR02**

## Surface Mounting Chip LED

S-GW Type

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	$P_{\mathrm{D}}$	60	mW	
Forward current	$I_{\mathrm{F}}$	I <sub>F</sub> 20		
Pulse forward current *	I <sub>FP</sub> 60		mA	
Reverse voltage	V <sub>R</sub>	4	V	
Operating ambient temperature	T <sub>opr</sub>	-25 to +85	°C	
Storage temperature	T <sub>stg</sub>	-30 to +100	°C	

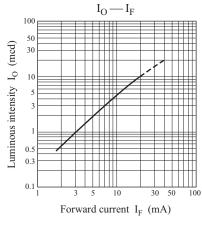
Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

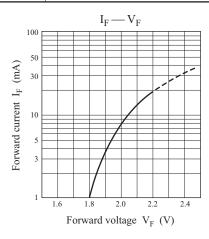
#### ■ Lighting Color

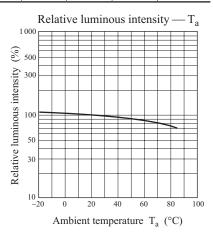
• Yellow Green

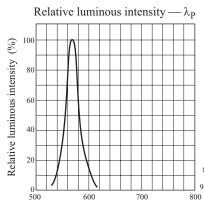
### ■ Electro-Optical Characteristics $T_a = 25$ °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I <sub>O</sub>	$I_F = 10 \text{ mA}$	3.0	5.0		med
Reverse current	$I_R$	$V_R = 4 V$			10	μΑ
Forward voltage	V <sub>F</sub>	$I_F = 10 \text{ mA}$		2.03	2.6	V
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 10 \text{ mA}$		565		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		30		nm

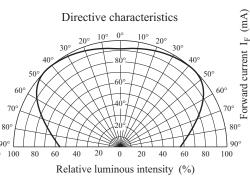


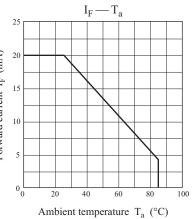






Peak emission wavelength  $\lambda_P$  (nm)

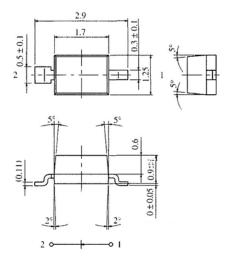




LNJ306G5TR02 Panasonic

■ Package (Unit: mm)

## LLTFTN2G0600



• Pin name

2

- 1: Anode
- 2: Cathode

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